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Erfinder: HIRASE KIYOTO

Anmelder: TOSHIBA CORP

Titel: DIE BONDING DEVICE

Zusammenfassung

PURPOSE: To simplify the mechanism of this device and enhance its general purpose properties by mounting a collet and a camera with an X-Y robot and driving the robot.

CONSTITUTION: A cassette ring 53 to which a semiconductor chip 50 to be assembled is laid out on a fixing member 52 and fixed thereto. Then, after it is laid out below a collet of the device, a user must align the chip 50 based on a screen of a monitor 67 and fix the chip. Then, the user positions a first chip 50 and starts bonding work. The difference between the chip position and a standard position previously stored in a position control means 66 is measured in conformity with die sorter test data, and X-axis motor 56 and a Y-axis motor 54 are driven so as to transfer the collet 62. Die bonding starts by operating a Z-axis motor 60. This construction makes it possible to obtain a low cost device whose mechanism and control system are simplified.

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